ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declarati the declaration e	on of the su	bstances v s all lower	vithin the manufactu level materials for v	rer listed which the	item. Note manufactu	: if the item is an a rer has engineering	ssembly with low responsibility.	
				Form Type Distribute					ials and Mfg Information					
upplier Information														
Company name* Cor			Company unique ID			Unique ID Authority				Respor	Response Date*			
onsemi										2025-0	2025-06-02			
ontact Name Title - Contact			t			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product 1			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	ctive Date Version Manufacturing St		lanufacturing Site		Weight*	UOM	Unit Type	
	MAX80	MAX809SQ308T1G ANA 3.		NA 3.08V MCROPROC RESET		2025-06-02		М	MY1		6.0	mg	Each	
Ianufacturing Proccess Informa	tion						-	·						
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy J-STD-020 MSL R		L Rating	Peak Proc	Process Body Temperatu		ure Max Time at Peak Temper		ture Nur	mber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alle		CU Alloy	1			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1	mg	Supplier	Silicon (Si)	7440-21-3		0.1	mg
Die Attach	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.1125	mg
			Supplier	Epoxy resins	129915-35-1		0.0375	mg
Lead Frame	1.93	mg	В	Nickel (Ni)	7440-02-0		0.7392	mg
			Supplier	Iron (Fe)	7439-89-6		1.021	mg
			Supplier	Copper (Cu)	7440-50-8		0.1698	mg
Mold Compound-Black	3.7	mg		Epoxy resin	proprietary data		0.185	mg
				Phenolic Resin	Proprietary Data		0.185	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.074	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0185	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.2375	mg
Plating	0.11	mg	Supplier	Tin (Sn)	7440-31-5		0.11	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg